

2009 International Workshop On EUV Lithography

July 13-17, 2009

Sheraton Waikiki Beach ■ Honolulu, Hawaii

Workshop Proceedings

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2009 International Workshop on EUV Lithography
Sheraton Waikiki Beach, Honolulu, Hawaii, USA
July 13-17, 2009

Workshop Agenda

(A) Lithography Education Series (July 13-14, 2009)

EUV Lithography

Kona Room, 8:00 AM -5:00 PM, Monday, July 13, 2009

Resist Materials for High Resolution Patterning

Kona Room, 6:00 PM-10:00 PM, Monday, July 13, 2009

EUV Physics

Kona Room, 8:00 AM – 12:00 PM, Tuesday, July 14, 2009

Introduction to Lithography

Kona Room, 1:00 PM – 5:00PM, Tuesday, July 14, 2009

(B) EUVL Workshop (July 14-17, 2009)

Tuesday, July 14, 2009

5:00 PM- 7:00 PM Reception (Helumoa Playground)
4:00 PM- 6:00 PM Registration & Speaker Prep (Lanai Room)

Wednesday, July 15, 2009

7:00 AM – 8:00 AM Continental Breakfast (Lanai Foyer)
8:00 AM – 12:00 PM Oral Presentations (Lanai Room)
12:00 PM – 1:00 PM Lunch (Honolulu Suite)
1:00 PM – 4:30 PM Oral Presentations (Lanai Room)
5:00 PM – 6:30 PM Poster Session and Reception (Honolulu Suite)
7:00 PM



Thursday, July 16, 2009

7:00 AM	-	8:00 AM	Continental Breakfast (Lanai Foyer)
8:00 AM	-	12:00 PM	Oral Presentations and Panel Discussions (Maui Room)
12:00 PM	-	1:00 PM	Lunch (Honolulu Suite)
1:00 PM	-	4:00 PM	Oral Presentations (Maui Room)
4:00 PM			Adjourn

Friday, July 17, 2009

8:30 AM	-	10:30 AM	Breakfast and Steering Committee Meeting (Honolulu Suite)
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WORKSHOP PROCEEDINGS

2009 International Workshop on EUV Lithography
Sheraton Waikiki Beach, Honolulu, Hawaii, USA
July 13-17, 2009

Wednesday, July 15, 2009

8:00 AM [Welcome and Introduction](#)

Vivek Bakshi
EUV Litho, Inc.

8:10 AM **Session 1: Keynote Presentations**

Session Chair: David Attwood (LBNL/ UC Berkeley)

[R&D Status and Key Technical and Implementation Challenges for EUV HVM](#) (KEY-1)

[Sam Sivakumar](#)
Intel Corporation

[Readiness and Challenges in EUV Mask Technology for 32nm-HP Node and Beyond](#) (KEY-2)

[Han-Ku Cho](#) and Seong-Sue Kim
Semiconductor R&D Center, Samsung Electronics Co., LTD.

9:10 AM **Award Ceremony**

9:10 AM **Session 2: EUV Source Technology**

Session Co-Chairs: Ndaona Chokani (ETHZ) and Padraig Dunne (UCD)



High Brightness Next Generation EUV Lithography Light Source (Source-1, Invited)

Peter CHOI ^{1,2}, Sergey V. ZAKHAROV ²⁺, Raul ALIAGA-ROSSEL ¹, Aldrice BAKOUBOULA ¹, Otman BENALI ^{1,2}, Philippe BOVE ¹, Michèle CAU ¹, Grainne DUFFY ¹, Sebastian FANT ², Blair LEBERT ², Ouassima SARROUKH ², Edmund WYNDHAM ³, Clement ZAEPFFEL ², Vasily S. ZAKHAROV ^{2*}

¹ NANO-UV sas, 16-18 av du Québec, SILIC 705, Villebon/Yvette 91140, France

² EPPRA sas, 16 av du Québec, SILIC 706, Villebon/Yvette 91140, France

³ Pontificia Universidad Catolica de Chile, Santiago, Chile

⁺ RRC Kurchatov Institute, Moscow, Russia

^{*} KIAM RAS, Moscow, Russia

Determination of Charge State, Energy and Angular Distribution of tin Ions Emitted from LPP EUV Sources (Source-2)

Oran Morris, Aodh O'Connor, Emma Sokell and Padraig Dunne

School of Physics, University College Dublin, Belfield, Dublin 4, Ireland

Molecular Dynamics Investigation on Tin (Source-7)

M. Masnavi, M. Nakajima and K. Horioka

Department of Energy Sciences, Tokyo Institute of Technology, Nagatsuta, Midori-ku, Yokohama 226-8502, Japan

Fiber Lasers for EUV Lithography (Source-6, Invited)

Almantas Galvanauskas, Kai-Chung Hou*, Cheng Zhu, P. Amaya+,
University of Michigan, Ann Arbor, MI, USA,

** Currently with Cymer, Inc.,*

+Arbor Photonics, Inc.

LPP EUV Source Development at ETHZ (Source-4)

B. Rollinger, A. Giovannini, D. Bleiner, N. Chokani, and R. S. Abhari

Laboratory for Energy Conversion, ETH Zurich, Sonneggstrasse 3, 8092 Zurich, Switzerland

High Power EUV Sources: Technology Status (Source-5)

Vivek Bakshi

EUVL Litho, Inc., Austin, TX 78748, USA

10:50 AM

Break (15 minutes)



11:05 AM

Session 3: EUV Optics

Session Chair: Patrick Naulleau (LBNL)

[Multilayer Optics for Next-generation EUVL Systems](#) (OP-1, Invited)

Regina Soufli

Lawrence Livermore National Laboratory, Livermore, CA 94550, USA

[Use of Free Form Optical Surfaces for EUVL Projection](#) (OP-2, Invited)

R. Hudyma and Mike Thomas

Hyperion Development LLC, 358 South Overlook Dr., San Ramon, CA 94582, USA

Technology Readiness for HVM Source Collector (OP-3)

Roland Geyl, Renaud Mercier Ythier

Sagem, Avenue de la Tour Maury, 911280 Saint Pierre du Perray FRANCE

12:00 PM

Lunch (Honolulu Suite)

1:00 PM

Session 4: METROLOGY

Session Co-Chairs: Regina Soufli (LLNL) and Charles Tario (NIST)

[High Accuracy EUV Reflectometry and Scattering at the Advanced Light Source](#) (MET-8, Invited)

Eric M. Gullikson

Center for X-Ray Optics, Lawrence Berkeley National Laboratory, One Cyclotron Road, Berkeley, CA 94720

[At-wavelength EUV metrology at NIST](#) (MET-4)

C. Tarrío, S. Grantham, R. E. Vest, P-S. Shaw T. B. Lucatorto

National Institute of Standards and Technology, 100 Bureau Drive, Gaithersburg, MD



EUV Reflectometry for Determining the Optical Properties of Photoresists and Underlayer Materials upon Irradiation at 13.5 nm (MET-7)

Grace H. Ho,¹ Fu-H. Kang,¹ Yu-H. Shih,¹ Hok-S. Fung,² Hwang-W. Fu,² Rikimaru Sakamoto,³ Takafumi Endo,³ Bang-C. Ho,³ Yang-T. Huang,⁴ and Bor-Y. Shew²

¹Department of Applied Chemistry, National University of Kaohsiung, Nanzih, Kaohsiung 811, Taiwan

²National Synchrotron Radiation Research Center, Hsinchu 311, Taiwan.

³Electronic Materials Research Laboratories, Nissan Chemical Industries, Ltd., Tayama 937-2792, Japan

⁴Department of Electronics Engineering, National Chiao Tung University, Hsinchu300, Taiwan

Hydrothermal method grown ZnO crystal as a fast EUV scintillator and EUV laser imaging device (MET-1, Invited)

T. Shimizu^{a,d}, K. Yamamoi^a, E. Estacio^a, T. Nakazato^{a,d}, N. Sarukura^{a,d}, Y. Kagamitani^b, D. Ehrentaut^b, T. Fukuda^{b,c},

^a Institute of Laser Engineering, Osaka Univ., 2-6 Yamadaoka, Suita, Osaka 565-0871, Japan

^b Institute of Multidisciplinary Research for Advanced Materials, Tohoku Univ.

^c WPI Advanced Institute for Materials Research Tohoku University

Development of X-ray Tool for Critical-Dimension Metrology (MET-2)

Boris Yokhin^{1*}, Alexander Krokhmal¹, Alexander Dikopoltsev¹, David Berman¹, Isaac Mazor¹, Byoung-Ho Lee², Dong-Chul Ihm² and Kwang Hoon Kim²

¹Jordan Valley Semiconductors Ltd., Ramat Gabriel Ind. Zone, Migdal Haemek, Israel, 23100

²Samsung Electronics, San#16 Banwol-dong, Hwasung-City, Gyeonggi-Do, Korea 445-701

Development of ultra-fine structure metrology system using coherent EUV source (MET-5)

Hiroo Kinoshita^{1,3}, Nagata Yutaka^{2,3}, Tetsuo Harada^{1,3}, and Takeo Watanabe^{1,3}

¹LASTI, University of Hyogo, 3-1-2, Koto, Kamigori, Ako, Hyogo, Japan 678-1205

²RIKEN Wakou

³JST CREST

2:40 PM

Break (20 Minutes)



3:00 PM Session 4: Contamination

Session Co-chairs: David Ruzic (UIUC) and Grace Ho (NUK)

[An Investigation of Debris Production by Various EUV Sources](#) (CONT-1, Invited)

D.N. Ruzic, J. Sporre, V. Surla, M.J. Neumann

Center for Plasma Material Interactions, Department of Nuclear Plasma and Radiological Engineering, University of Illinois at Urbana-Champaign, IL, USA

[Modification of Ru Surfaces during Simultaneous Irradiation of Thermalized and Energetic Sn particles at Grazing Incidence](#) (CONT-2, Invited)

V. Rigato

INFN Laboratori Nazionali di Legnaro, Italy

[Predicting optics carbonization from a knowledge of resist outgas composition](#) (CONT-3)

C. Tarrio,¹ S. B. Hill,¹ N. Faradzhev,² R. E. Vest,¹ R. Garg,³ T. B. Lucatorto¹

¹*National Institute of Standards and Technology*

²*Rutgers University*

³*University at Albany*

[Absolute Total Ion Yield and the Relative Extent of Ionic Outgassing of Photoresists and Underlayer Materials upon Irradiation at 13.5 nm](#)

(CONT-4)

Grace H. Ho, Yu-H. Shih, and Fu-H. Kang

Department of Applied Chemistry, National University of Kaohsiung, Nanzih, Kaohsiung 811, Taiwan

[EUV Mask and Optics Contamination](#) (CONT-5)

G. Denbeaux, Leonid Yankulin, Yu-Jen Fan, R. Garg, Chimaobi Mbanaso, Petros Thomas, Alin Antohe

College of Nanoscale Science and Engineering, University at Albany, NY, USA

4:30 PM BREAK (30 Minutes)

5:00 PM – 6:30 PM Poster Session and Reception



5:00 PM Session 5: Poster Session

Session Chair: Ken Goldberg (LBNL)

1-D Plasma Modeling with Radiation Transport (Source-3)

J. White, A. Cummings, P. Dunne, and G. O'Sullivan,
School of Physics, University College Dublin, Ireland

Tabletop Synchrotron for Actinic Defect Inspection of EUVL Mask (Source-9)

H. Yamada, Y. Shimura, D. Minkov, S. Narita and K. Igarashi
Ritsumeikan University, Kusatsu, Shiga Prefecture, Japan

Resist Transmission Measurement using EUV Light (MET-3)

Takeo Watanabe, Yasuyuki Fukushima, Tetsuo Harada, and Hiroo Kinoshita
*Laboratory of advanced Science and Technology for Industry, University of Hyogo,
Hyogo 678-1205, Japan*

A Compact and Ultrahigh-vacuum Reflectometer for EUV Applications (MET-6)

Hwang-W. Fu,¹ Grace H. Ho,² Liang-J. Huang,¹ Chia-F. Chang,¹ Shang-W. Lin,¹
Shiang-W. Luo,¹ Fu-H. Kang,² Yuh-H. Shih,² Hok-S. Fung,¹ and Bor-Y. Shew¹
¹*National Synchrotron Radiation Research Center, Hsinchu 311, Taiwan.*
²*Department of Applied Chemistry, National University of Kaohsiung, Nanzih,
Kaohsiung 811, Taiwan*

An Investigation of the Impact of Mask Shadowing Effect on Flare in Extreme Ultraviolet Lithography (MASK-1)

Jun-Hwan Lee, O-Hyun Kim
*Department of Electronic and Electrical Engineering,
Pohang University of Science and Technology, South Korea*

Development of Mask Contamination/Inspection System for EUV Lithography (MASK-2)

Sangsul Lee^{1,2}, Chang Young Jeong¹, Dong Geun Lee³, Seong-Sue Kim³, Han-Ku Cho³,
Seung-yu Rah⁴, Ohyun Kim⁵, Moonsuk Yi⁶ and Jinho Ahn¹

¹ *Department of Materials Science and Engineering, Hanyang University*

² *Information Display Research Institute, Hanyang University*

³ *Photomask Team, Memory Division, Semiconductor Business, Samsung Electronics Co., LTD*

⁴ *Pohang Accelerator Laboratory*

⁵ *Department of Electrical Engineering, Pohang University of Science and Technology*

⁶ *School of Electrical and Computer Engineering, Pusan National University*



Optimizing Structure of Attenuated Phase Shift Mask for Minimizing Shadowing Effect (MASK-7)

Hyun-Duck Shin¹, Chang Young Jeong², Sangsul Lee², Tae Geun Kim², and Jinho Ahn²

¹Department of Nanoscale Semiconductor Engineering, Hanyang University, Korea

²Department of Material Science and Engineering, Hanyang University, Korea

Line Width Roughness Investigation through Resist Molecular Structure in Extreme Ultra-violet Lithography (Resist-3)

Hyunsu Kim¹, In Wook Cho², Hakjin Jang³, Mihwa Kang³, Seong Wook Kim³ and Hye-Keun Oh²

¹ Department of Bio-Nanotechnology, HanyangUniversity, Ansan, 426-791, Korea

² Department of Applied Physics, HanyangUniversity, Ansan, 426-791, Korea

³ Department of Applied Mathematics, HanyangUniversity, Ansan, 426-791, Korea

Dependence of Acid Yield on Polymer Structure in EUV Chemically Amplified Resist (RESIST-5)

Hiroki Yamamoto¹, Takahiro Kozawa¹, Seiichi Tagawa¹, Takeshi Iwai², and Junichi Onodera²

¹The Institute of Scientific and Industrial Research, Osaka University (ISIR), Japan

²Tokyo Ohka Kogyo Co., Ltd. (TOK), Japan

7:00 PM

Dinner (Rum Fire)



Thursday, July 16, 2009

8:00 AM [Welcome Day-2 Agenda](#)

Vivek Bakshi
EUV Litho, Inc.

8:05 AM Poster Session Awards, Ken Goldberg, LBNL

8:10 AM Session 7: Panel Discussion
Panel Discussion Moderator: David Attwood (LBNL)

Topic: EUVL R&D Status

Panelists:

[US EUVL R&D Status](#) (R&D-1)

Greg Denbeaux – USA
University of Albany, NY

[EUVL Development Projects in Japan](#) (R&D-2)

Hiroo Kinoshita –Japan
Hyogo University, Japan

[The European Perspective: EUVL R&D Status](#) (R&D-3)

Padraig Dunne – Europe
University College, Dublin, Ireland

[An Overview of EUVL Related R&D in Taiwan](#) (R&D-4)

Grace Ho – Taiwan
National University of Kaohsiung, Taiwan

[EUVL R&D Status of Korea](#) (R&D-5)

Jinho Ahn – Korea
Hanyang University, Korea



9:00 AM Session 8: EUV Mask

Session Co-Chairs: Hiroo Kinoshita (Hyogo University) and Jinho Ahn (Hanyang University)

[Optimizing the Mask Structure for Extreme Ultraviolet Lithography](#) (MASK-6, Invited)

Chang Young Jeong, Sangsul Lee, Hyun-Duck Shin, Tae Geun Kim, and Jinho Ahn
Department of Materials Science and Engineering, Hanyang University, 17 Haengdang-Dong, Seoul, 133-791, Korea

[Wavelength-Specific Reflections: A Decade of EUV Mask Inspection Research](#) (MASK-4, Invited)

Kenneth A. Goldberg¹, Iacopo Mochi¹, Sungmin Huh²

¹*Lawrence Berkeley National Laboratory*

²*SEMATECH*

[Study of Critical Dimensions of Printable Phase Defects Using an Extreme Ultraviolet microscope](#) (MASK-3, Invited)

Hiroo Kinoshita^{1, 3}, Yoshito Kamaji^{1, 3}, Kei Takase^{1, 3}, Takashi Sugiyama², Toshiyuki Uno², Tetsuo Harada¹ and Takeo Watanabe^{1, 3}

¹*Laboratory of Advanced Science and Technology for Industry, University of Hyogokamigori, Ako-gun, Hyogo 678-1205, Japan*

²*Asahi Glass Co., Ltd., R&D Center, Yokohama 221-8755, Japan*

³*JST, CREST, Yonban, Chiyoda, Tokyo 102-0081, Japan*

[Zoneplate lenses for EUV microscopy](#) (MASK-5)

Iacopo Mochi¹, Kenneth A. Goldberg¹, Erik H. Anderson¹, Sungmin Huh²

¹*Lawrence Berkeley National Laboratory*

²*SEMATECH*

10: 15 AM Break (15 Minutes)



10:30 AM

Session 9: Panel Discussion

Panel Discussion Moderator: Vivek Bakshi (EUV Litho, Inc.)

Topic: Actinic Defect Inspection Technology for EUVL Masks

[Introduction: Actinic Mask Defect Inspection: Are EUV Sources Available?](#)

(Mask Panel-1)

Vivek Bakshi

EUV Litho, Inc.

Panelists:

[Requirements of EUV Light Source for Actinic Mask Inspection](#) (Mask Panel-2)

Takeo Watanabe and Hiroo Kinoshita

Hyogo University

[EQ-10 EUV Source for Actinic Inspection](#) (Mask Panel-3)

Debbie Gustafson

Energetiq

[High Brightness EUV Light Source for Metrology](#) (Mask Panel-4)

Sergey Zakharov

Nano UV

[Compact Optical Undulator Technology for a High Brightness EUV Lithography Source](#) (Mask Panel-5)

John M. J. Madey, Eric B. Szarmes, Mike Hadmack, Bryce Jacobson, and Shidong Kan

Department of Physics and Astronomy, University of Hawai'i at Manoa

[Tabletop Synchrotron for Actinic Defect Inspection of EUVL Mask](#) (Mask Panel-6)

H. Yamada, Y. Shimura, D. Minkov, S. Narita and K. Igarashi

Ritsumeikan University, Kusatsu, Shiga Prefecture, Japan

&

Photon Production Lab. Ltd.



Actinic Mask Defect Inspection: EUV Source Technology Status (Mask Panel-7)

Vivek Bakshi
EUV Litho, Inc.

12:00 PM – 1:00 PM Lunch

1:00 PM Session 10: EUV Resist

***Session Co-Chairs: Takahiro Kozawa (Osaka University) and
Chris Mack (Lithoguru.com)***

Development Status and Future Prospect of Extreme Ultraviolet Resists

(Resist -9, Invited)

Takahiro Kozawa

The Institute of Scientific and Industrial Research, Osaka University (ISIR), Japan

Improvement of EUV Resist Materials (Resist-1, Invited)

Jeongsik KIM, Jungyoul LEE, Jae-Woo LEE, Deog- Bae KIM, Jaehyun KIM
*Dongjin Semichem CO., Ltd, 625-3 Yodang-Ri, Yanggam-Myun, Hwasung-Si,
Gyeonggi-Do, 445-931 KOREA*

**Molecular Resist Materials for Next Generation Lithography: A Rich
Diversity of Possibilities** (Resist-11, Invited)

Clifford L. Henderson¹, Richard A. Lawson¹, Laren M. Tolbert²

¹ *School of Chemical & Biomolecular Engineering, Georgia Institute of Technology,
Atlanta, GA 30332-0100, USA*

² *School of Chemistry and Biochemistry, Georgia Institute of Technology, Atlanta,
GA 30332, USA*

EUV Interference Lithography (Resist-10, Invited)

Harun H. Solak^{1,2}, V. Auzelyte¹, A. Langner¹, S. S. Sarkar¹, A. Weber¹, H.
Pruchova¹, M. Kropf¹, C. David¹, J. Gobrecht¹

¹ *Paul Scherrer Institut, Lab for Micro and Nanotechnology, Villigen 5232,
Switzerland*

² *EULITHA AG, 5232 Villigen PSI, Switzerland*



[EUV Interference Lithography in New SUBARU](#) (Resist-6)

Takeo Watanabe¹, Tae Geun Kim^{1, 2}, Tetsuo Harada¹, Yasuyuki Fukushima¹, and Hiroo Kinoshita¹

¹ *Laboratory of advanced Science and Technology for Industry, University of Hyogo, Hyogo 678-1205, Japan*

² *Division of Advanced Materials Science and Engineering, Hanyang University, Seoul 133-791, Korea*

[Monte Carlo Simulation of Chemical Intermediates in CARs](#) (Resist-4)

A. Saeki, T. Kozawa, and S. Tagawa

The Institute of Scientific and Industrial Research, Osaka University, 8-1 Mihogaoka, Ibaraki, Osaka 567-0047, Japan

2:50 PM Break (15 minutes)

3:05 PM Session 11: LER

Session Chair: Cliff Henderson (Georgia Tech)

[Stochastic Approach to Modeling Line Edge Roughness in Photolithography](#)

(Resist-8, Invited)

Chris Mack

Lithoguru.com, 1605 Watchhill Rd., Austin, TX 78703

[How Will Wafer Plane Line-edge Roughness Requirements Impact Mask Specifications?](#) (Resist-7, Invited)

Patrick P. Naulleau and Simi A. George

Center for X-Ray Optics, Lawrence Berkeley National Laboratory, Berkeley, CA 94720

[Sub-22 nm Line and Space patterning using Resist Reflow Process for Extreme Ultra-Violet Lithography](#) (Resist-2)

In Wook Cho, Hyunsu Kim, Jee-Hye You, Hye-Keun Oh

Lithography Laboratory, Department of Applied Physics, Hanyang University, Ansan, 426-791, S. Korea

4:00 PM [WORKSHOP SUMMARY](#)

Vivek Bakshi

EUV Litho Inc.

4:10 PM Adjourn